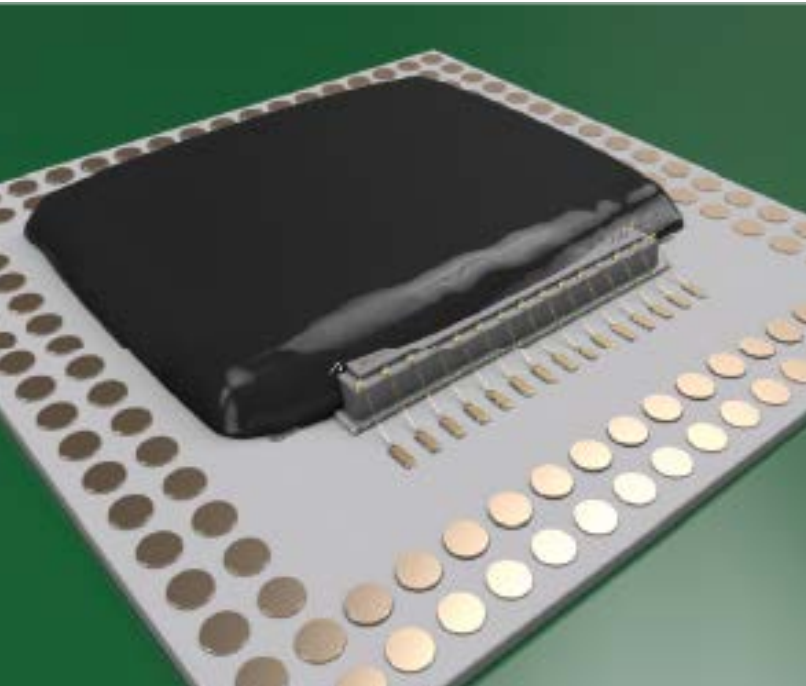


# GLOB TOP & ENCAPSULANT MATERIALS

*When things go “bump,” nobody protects you better than NAMICS*

NAMICS' glob tops and encapsulants are electrical insulating materials used for both environmental protection and enhanced mechanical robustness. These materials are ideal for fragile semiconductor devices and components, as well as wire bond packages. Offering exceptional moisture protection and unmatched performance, NAMICS' glob top and encapsulant materials are perfect for the most demanding applications. These materials are designed for high-speed manufacturing operations through fast curing profiles and easy dispensing through either needle or jet.



- Outstanding adhesion to a wide variety of substrates
- Low CTE and high modulus for unmatched strength
- REACH and RoHS compliant
- High moisture and heat resistance
  - ❖ *High reliability for harsh environment applications*
  - ❖ *Superior moisture resistance*
  - ❖ *High bias voltage to protect critical components*

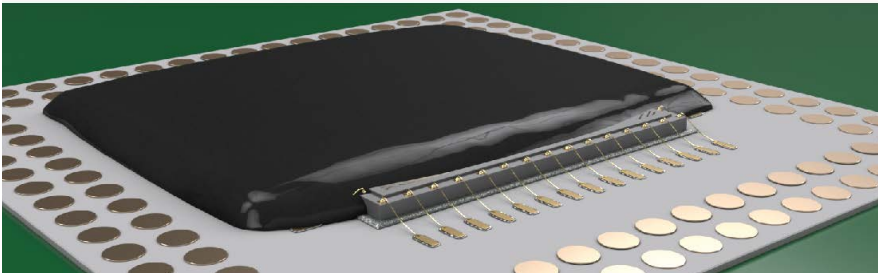
NAMICS Technologies, Inc.

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# MATERIAL OVERVIEW



## GLOB TOP ENCAPSULATION



- ▶ NAMICS' encapsulants are used for glob top encapsulation by dispensing a precise volume of material on the component with controlled flow over the target area.

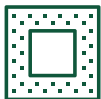
## DAM & FILL ENCAPSULATION



- ▶ NAMICS' encapsulants can be used in a two-step dam and fill process.



Halogen free and meets key environmental requirements



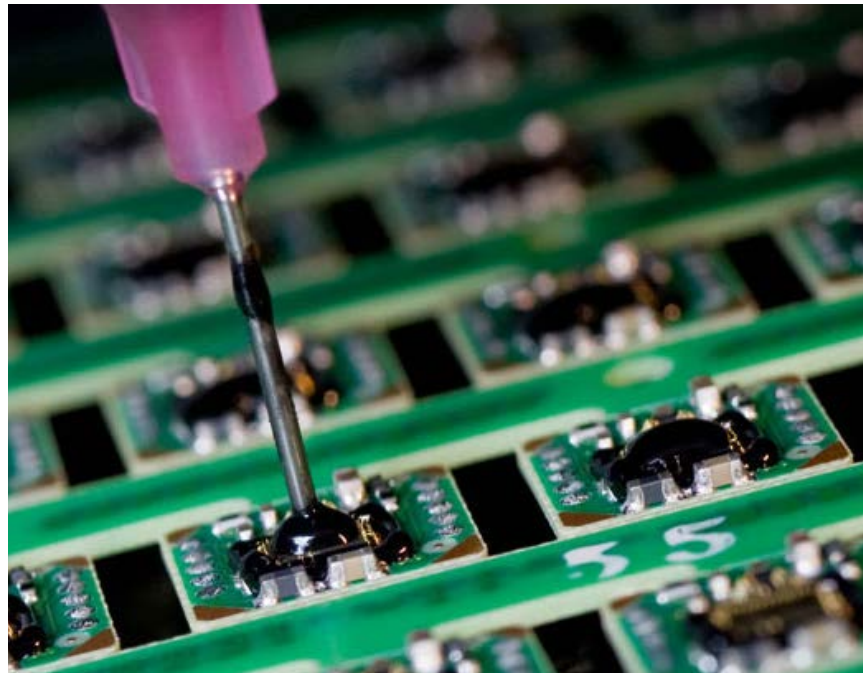
Unmatched reliability and moisture protection for harsh environments



Fast curing by using heat for shorter production cycles



Controlled rheology with high aspect ratio for dam applications, and excellent flow for fill applications



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